

RELIABILITY MONITOR

STRESS: WRITE CYCLE STRESS

CONDITIONS: 85 C, 7.0 VOLTS

PRODUCT	REV	MONITOR DATE	JOB NO	DATE ASSEMBLY CODE FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAIL
DS1621	A7	MAR '00	25224	9950 OSEP	DE940040AAC	SOIC	50	50	0

RELIABILITY MONITOR

STRESS: VAPOR PHASE REFLOW

CONDITIONS: 217C

PRODUCT	REV	MONITOR DATE	JOB NO	DATE ASSEMBLY CODE FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAIL
DS5002	C4	APR '00	25428	0004 Carsem	DM925587AAF	MQFP	3	203	0
DS87C520	A14	FEB '00	25118	0004 ATP (Anam, PI)	DK935356AAB	PLCC	3	233	0

RELIABILITY MONITOR

STRESS: VAPOR PHASE REFLOW

CONDITIONS: 220C

PRODUCT	REV	MONITOR DATE	JOB NO	DATE ASSEMBLY CODE FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAIL
DS5002	C5	JUL '00	25824	0027 ATK (Anam, K)	DN012259AAL	MQFP	3	203	0
DS87C520	A15	AUG '00	25864	0027 OSEP	DE013425AAD	PLCC	3	239	0

RELIABILITY MONITOR

STRESS: ULTRASOUND

CONDITIONS: J-STD-020

PRODUCT	REV	MONITOR		DATE ASSEMBLY		LOT NO.	PACKAGE	READ	
		DATE	JOB NO	CODE	FACILITY			POINT	QTY
DS1232	C2-L	JAN '00	25019	9948	ATP (Anam, PI)	DK933191AAJ	SOIC	4	0
DS1232	C2-L	APR '00	25418	0011	OSEP	DE952427AAD	SOIC	4	0
DS1232	C2-L	JUL '00	25784	0024	OSEP	DE014522ADB	SOIC	4	0
DS1232	C2-L	OCT '00	26086	0039	OSEP	DE028679ADB	SOIC	4	0
DS1267	A2	FEB '00	25172	9930	ATP (Anam, PI)	DK904472ADF	TSSOP	4	0
DS1621	A7	MAR '00	25217	9950	OSEP	DE940040AAC	SOIC	4	0
DS1869	A3	JUN '00	25540	0017	CPS (ChipPac, China)	DH833210AAB	SOIC	4	0
DS2108	B7	MAY '00	25522	0019	ATP (Anam, PI)	DK007198AAF	SOIC	4	0
DS2108	B7	AUG '00	25854	0029	ATP (Anam, PI)	DK016058AA	SOIC	4	0
DS2154	A2	JUN '00	25617	0022	ATK (Anam, K)	DN012234ABA	LQFP	4	0
DS2181A	A2	JUL '00	25815	0016	OSEP	DE004552ABD	PLCC	4	0
DS21Q43	A3-A	JUN '00	25501	0014	ATK (Anam, K)	DN004571AAB	LQFP	4	0
DS21S07	C1-	MAY '00	25443	0013	Carsem S	DM002285AAF	TSSOP	4	0
DS2502	C3	MAR '00	25250	0005	Carsem S	DM941226AA	SOIC	4	0
DS2502	C3	JUN '00	25565	0011	Carsem S	DM941230AG	SOIC	4	0
DS5002	C4	APR '00	25427	0004	Carsem	DM925587AAF	MQFP	4	0
DS87C520	A14	FEB '00	25117	0004	ATP (Anam, PI)	DK935356AAB	PLCC	4	0
DS87C520	A15	AUG '00	25863	0027	OSEP	DE013425AAD	PLCC	4	0

RELIABILITY MONITOR

STRESS: TEMP CYCLE

CONDITIONS: -40 TO 85C

PRODUCT	REV	MONITOR DATE	JOB NO	DATE ASSEMBLY CODE	FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAIL
DS2250	E-T	SEP '00	25963	0035	Fastech	117888	SipStick w/Confor	100	11	0

RELIABILITY MONITOR

STRESS: TEMP CYCLE

CONDITIONS: -55C TO 125C

PRODUCT	REV	MONITOR		DATE ASSEMBLY		LOT NO.	PACKAGE	READ		
		DATE	JOB NO	CODE	FACILITY			POINT	QTY	FAIL
DS1232	C2-L	JAN '00	25024	9948	ATP (Anam, PI)	DK933191AAJ	SOIC	300	40	0
DS1232	C2-L	JAN '00	25024	9948	ATP (Anam, PI)	DK933191AAJ	SOIC	1000	38	0
DS1232	C2-L	APR '00	25423	0011	OSEP	DE952427AAD	SOIC	300	40	0
DS1232	C2-L	APR '00	25423	0011	OSEP	DE952427AAD	SOIC	1000	40	0
DS1232	C2-L	JUL '00	25789	0024	OSEP	DE014522ADB	SOIC	300	40	0
DS1232	C2-L	JUL '00	25789	0024	OSEP	DE014522ADB	SOIC	1000	40	0
DS1267	A2	FEB '00	25177	9930	ATP (Anam, PI)	DK904472ADF	TSSOP	300	36	0
DS1302	A3	MAR '00	25213	0006	CPS (ChipPac, China)	DH945115AAB	PDIP	300	40	0
DS1302	A3	MAR '00	25213	0006	CPS (ChipPac, China)	DH945115AAB	PDIP	1000	40	0
DS1302	A3	JUN '00	25537	0018	CPS (ChipPac, China)	DH008331AAA	PDIP	300	40	0
DS1302	A3	JUN '00	25537	0018	CPS (ChipPac, China)	DH008331AAA	PDIP	1000	39	0
DS1302	A3	AUG '00	25933	0032	CPS (ChipPac, China)	DH020619AAA	PDIP	300	40	0
DS1621	A7	MAR '00	25222	9950	OSEP	DE940040AAC	SOIC	300	40	0
DS1621	A7	MAR '00	25222	9950	OSEP	DE940040AAC	SOIC	1000	40	0
DS2108	B7	MAY '00	25527	0019	ATP (Anam, PI)	DK007198AAF	SOIC	300	40	0
DS2108	B7	MAY '00	25527	0019	ATP (Anam, PI)	DK007198AAF	SOIC	1000	40	0
DS2108	B7	AUG '00	25859	0029	ATP (Anam, PI)	DK016058AA	SOIC	300	40	0
DS2108	B7	AUG '00	25859	0029	ATP (Anam, PI)	DK016058AA	SOIC	1000	40	0
DS2118M	B1	SEP '00	25945	0033	ATK (Anam, K)	DN020718AAD	SSOP	300	77	0
DS2118M	B1	SEP '00	25945	0033	ATK (Anam, K)	DN020718AAD	SSOP	1000	77	0
DS2154	A2	JUN '00	25622	0022	ATK (Anam, K)	DN012234ABA	LQFP	300	73	0
DS2154	A2	JUN '00	25622	0022	ATK (Anam, K)	DN012234ABA	LQFP	1000	73	1

RELIABILITY MONITOR

STRESS: TEMP CYCLE

CONDITIONS: -55C TO 125C

PRODUCT	REV	MONITOR		DATE ASSEMBLY		LOT NO.	PACKAGE	READ		
		DATE	JOB NO	CODE	FACILITY			POINT	QTY	FAIL
DS2154	A2	SEP '00	25960	0034	ATP (Anam, PI)	DK022283AAA	LQFP	300	63	0
DS2154	A2	SEP '00	25960	0034	ATP (Anam, PI)	DK022283AAA	LQFP	1000	63	0
DS21Q43	A3-A	JUN '00	25506	0014	ATK (Anam, K)	DN004571AAB	LQFP	300	70	0
DS21S07	C1-	MAY '00	25448	0013	Carsem S	DM002285AAF	TSSOP	300	40	0
DS21S07	C1-	MAY '00	25448	0013	Carsem S	DM002285AAF	TSSOP	1000	40	0
DS2401	C2	SEP '00	25967	0034	Fastech	DA005635AKA	TO92	300	40	0
DS2401	C2	SEP '00	25967	0034	Fastech	DA005635AKA	TO92	1000	40	0
DS2434	D1	AUG '99	24393	9837	Carsem	DM811482AA	TO226 (PR35)	300	50	0
DS2434	D1	AUG '99	24393	9837	Carsem	DM811482AA	TO226 (PR35)	1000	50	1
DS2502	C3	MAR '00	25255	0005	Carsem S	DM941226AA	SOIC	300	39	0
DS2502	C3	MAR '00	25255	0005	Carsem S	DM941226AA	SOIC	1000	38	0
DS2502	C3	JUN '00	25570	0011	Carsem S	DM941230AG	SOIC	300	34	0
DS2502	C3	JUN '00	25570	0011	Carsem S	DM941230AG	SOIC	1000	34	0
DS2502	C3	JUL '00	25813	0017	CPS (ChipPac, China)	DH948636AG	TSOC	300	72	0
DS5002	C4	APR '00	25432	0004	Carsem	DM925587AAF	MQFP	300	40	0
DS5002	C4	APR '00	25432	0004	Carsem	DM925587AAF	MQFP	1000	40	0
DS5002	C5	JUL '00	25828	0027	ATK (Anam, K)	DN012259AAL	MQFP	300	37	0
DS80C320	C5	JAN '00	25016	0001	CPS (ChipPac, China)	DH928322BAA	PDIP	300	40	0
DS80C320	C5	JAN '00	25016	0001	CPS (ChipPac, China)	DH928322BAA	PDIP	1000	40	0
DS80C320	C5	OCT '00	26066	0038	CPS (ChipPac, China)	DH026369ABA	PDIP	300	40	0
DS87C520	A14	FEB '00	25122	0004	ATP (Anam, PI)	DK935356AAB	PLCC	300	40	0
DS87C520	A14	FEB '00	25122	0004	ATP (Anam, PI)	DK935356AAB	PLCC	1000	39	0

RELIABILITY MONITOR

STRESS: TEMP CYCLE

CONDITIONS: 0C TO 70C

PRODUCT	REV	MONITOR DATE	JOB NO	DATE ASSEMBLY CODE	FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAIL
DS1230	B1-Y	APR '00	25415	0005	Fastech	118511	Module w/SMT	300	100	0
DS1230	B1-Y	APR '00	25415	0005	Fastech	118511	Module w/SMT	1000	100	0
DS1230	B1-	JUL '00	25778	0019	Fastech	117143	Module w/SMT	300	100	1
DS1230	B1-	JUL '00	25778	0019	Fastech	117143	Module w/SMT	1000	99	0
DS1230	B1-Y	JUL '00	25782	0020	Fastech	11387	Low Profile Module	300	77	0
DS1230	A1-Y	OCT '00	26097	0039	Fastech	120544	Module w/SMT	300	100	0
DS12887	A2-	JUL '00	25808	0027	Fastech	300063	Module w/Bent Fra	300	100	0
DS12887	A2-	JUL '00	25808	0027	Fastech	300063	Module w/Bent Fra	1000	100	0
DS12887	A2-	OCT '00	26072	0040	Fastech	300402	Module w/Bent Fra	300	100	0
DS1643	C1	AUG '99	24351	9929	Dallas	111344	Module w/Hi Densit	300	77	0
DS1643	C1	AUG '99	24351	9929	Dallas	111344	Module w/Hi Densit	1000	77	0
DS1643	C1	AUG '00	25920	0033	Fastech	121538	Module w/Hi Densit	300	77	0
DS1643	C1	AUG '00	25920	0033	Fastech	121538	Module w/Hi Densit	1000	77	1
DS1643	C1	NOV '00	26181	0042	Fastech	122271	Module w/Hi Densit	300	77	0
DS1644	B2	MAY '00	25685	0021	Dallas	119504	Power Cap	300	77	0
DS1644	B2	MAY '00	25685	0021	Dallas	119504	Power Cap	1000	77	0
DS1991	E8	JUN '00	25550	0021	Dallas	DS950013AA-	T5 w/welded Tabs	300	77	0
DS1991	E8	JUN '00	25550	0021	Dallas	DS950013AA-	T5 w/welded Tabs	1000	77	0
DS1991	F1	SEP '00	25938	0036	Dallas	DS922809AA-	Puk Can F50 Rev B	300	77	0
DS1991	F1	SEP '00	25938	0036	Dallas	DS922809AA-	Puk Can F50 Rev B	1000	77	0
DS5000	D6-T	FEB '00	25199	0006	Dallas	115605	SBDIP	300	15	0
DS5000	D6-T	FEB '00	25199	0006	Dallas	115605	SBDIP	1000	15	0

RELIABILITY MONITOR

STRESS: TEMP CYCLE

CONDITIONS: 0C TO 70C

PRODUCT	REV	MONITOR DATE	JOB NO	DATE ASSEMBLY CODE FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAIL
DS5000	D6-T	MAY '00	25533	0020 Dallas	117838	SBDIP	300	15	0
DS5000	D6-T	MAY '00	25533	0020 Dallas	117838	SBDIP	1000	15	0

RELIABILITY MONITOR

STRESS: STORAGE LIFE

CONDITIONS: 150C

PRODUCT	REV	MONITOR DATE	JOB NO	DATE ASSEMBLY CODE FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAIL
DS1621	A7	MAR '00	25225	9950 OSEP	DE940040AAC	SOIC	336	50	0
DS2502	C3	MAR '00	25257	0005 Carsem S	DM941226AA	SOIC	336	39	0
DS2502	C3	MAR '00	25257	0005 Carsem S	DM941226AA	SOIC	1000	39	0
DS2502	C3	JUN '00	25572	0011 Carsem S	DM941230AG	SOIC	336	34	0
DS2502	C3	JUN '00	25572	0011 Carsem S	DM941230AG	SOIC	1000	34	0
DS87C520	A14	FEB '00	25124	0004 ATP (Anam, PI)	DK935356AAB	PLCC	336	50	0
DS87C520	A14	FEB '00	25124	0004 ATP (Anam, PI)	DK935356AAB	PLCC	1000	50	0

RELIABILITY MONITOR

STRESS: STORAGE LIFE

CONDITIONS: 70C

PRODUCT	REV	MONITOR		DATE ASSEMBLY		LOT NO.	PACKAGE	READ		
		DATE	JOB NO	CODE	FACILITY			POINT	QTY	FAIL
DS1230	B1-Y	JUL '00	25781	0020	Fastech	11387	Low Profile Module	336	77	0
DS1643	C1	AUG '99	24350	9929	Dallas	111344	Module w/Hi Densit	336	77	0
DS1643	C1	AUG '99	24350	9929	Dallas	111344	Module w/Hi Densit	1000	77	0
DS1643	C1	AUG '00	25919	0033	Fastech	121538	Module w/Hi Densit	336	77	0
DS1643	C1	AUG '00	25919	0033	Fastech	121538	Module w/Hi Densit	1000	77	0
DS1643	C1	NOV '00	26180	0042	Fastech	122271	Module w/Hi Densit	336	77	0
DS1644	B2	MAY '00	25684	0021	Dallas	119504	Power Cap	336	77	0
DS1644	B2	MAY '00	25684	0021	Dallas	119504	Power Cap	1000	77	0
DS1991	E8	JUN '00	25549	0021	Dallas	DS950013AA-	T5 w/welded Tabs	336	77	0
DS1991	E8	JUN '00	25549	0021	Dallas	DS950013AA-	T5 w/welded Tabs	1000	77	0
DS1991	F1	SEP '00	25937	0036	Dallas	DS922809AA-	Puk Can F50 Rev B	336	77	0
DS5000	D6-T	FEB '00	25198	0006	Dallas	115605	SBDIP	336	15	0
DS5000	D6-T	FEB '00	25198	0006	Dallas	115605	SBDIP	1000	15	0
DS5000	D6-T	MAY '00	25532	0020	Dallas	117838	SBDIP	336	15	0
DS5000	D6-T	MAY '00	25532	0020	Dallas	117838	SBDIP	1000	15	0

RELIABILITY MONITOR

STRESS: STORAGE LIFE

CONDITIONS: 85C

PRODUCT	REV	MONITOR DATE	JOB NO	DATE ASSEMBLY CODE FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAIL
DS1230	B1-Y	APR '00	25414	0005 Fastech	118511	Module w/SMT	48	200	0
DS1230	B1-	JUL '00	25777	0019 Fastech	117143	Module w/SMT	48	200	0
DS1230	A1-Y	OCT '00	26096	0039 Fastech	120544	Module w/SMT	48	200	0
DS2250	E-T	SEP '00	25962	0035 Fastech	117888	SipStick w/Confor	336	11	0

RELIABILITY MONITOR

STRESS: SOLDERABILITY

CONDITIONS: MIL-STD-883-2003

PRODUCT	REV	MONITOR		DATE ASSEMBLY		LOT NO.	PACKAGE	READ	
		DATE	JOB NO	CODE	FACILITY			POINT	QTY
DS1230	B1-Y	APR '00	25412	0005	Fastech	118511	Module w/SMT	3	0
DS1230	B1-	JUL '00	25775	0019	Fastech	117143	Module w/SMT	3	2
DS1230	A1-Y	OCT '00	26094	0039	Fastech	120544	Module w/SMT	3	0
DS12887	A2-	JUL '00	25805	0027	Fastech	300063	Module w/Bent Fra	3	0
DS12887	A2-	OCT '00	26069	0040	Fastech	300402	Module w/Bent Fra	3	0
DS1643	C1	AUG '99	24348	9929	Dallas	111344	Module w/Hi Densit	3	0
DS1643	C1	AUG '00	25917	0033	Fastech	121538	Module w/Hi Densit	3	0
DS1643	C1	NOV '00	26178	0042	Fastech	122271	Module w/Hi Densit	3	0
DS5000	D6-T	MAY '00	25530	0020	Dallas	117838	SBDIP	3	0

RELIABILITY MONITOR

STRESS: SOLDER HEAT

CONDITIONS: HTC VAPOR PHASE

PRODUCT	REV	MONITOR DATE	JOB NO	DATE ASSEMBLY CODE FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAIL
DS2181A	A2	JUL '00	25816	0016 OSEP	DE004552ABD	PLCC	3	241	0

RELIABILITY MONITOR

STRESS: PRECONDITION U/S

CONDITIONS: J-STD-020

PRODUCT	REV	MONITOR		DATE	ASSEMBLY		LOT NO.	PACKAGE	READ	
		DATE	JOB NO		CODE	FACILITY			POINT	QTY
DS1232	C2-L	JAN '00	25021	9948	ATP (Anam, PI)		DK933191AAJ	SOIC	4	0
DS1232	C2-L	JUL '00	25786	0024	OSEP		DE014522ADB	SOIC	4	0
DS1232	C2-L	OCT '00	26088	0039	OSEP		DE028679ADB	SOIC	4	0
DS1267	A2	FEB '00	25174	9930	ATP (Anam, PI)		DK904472ADF	TSSOP	4	0
DS1621	A7	MAR '00	25219	9950	OSEP		DE940040AAC	SOIC	4	0
DS1869	A3	JUN '00	25542	0017	CPS (ChipPac, China)		DH833210AAB	SOIC	4	0
DS2108	B7	MAY '00	25524	0019	ATP (Anam, PI)		DK007198AAF	SOIC	4	0
DS2108	B7	AUG '00	25856	0029	ATP (Anam, PI)		DK016058AA	SOIC	4	0
DS2154	A2	JUN '00	25619	0022	ATK (Anam, K)		DN012234ABA	LQFP	4	0
DS2175	D1	OCT '00	26107	0042	ATP (Anam, PI)		DK031506AAC	SOIC	4	0
DS2181A	A2	JUL '00	25817	0016	OSEP		DE004552ABD	PLCC	4	0
DS21Q43	A3-A	JUN '00	25503	0014	ATK (Anam, K)		DN004571AAB	LQFP	4	0
DS21S07	C1-	MAY '00	25445	0013	Carsem S		DM002285AAF	TSSOP	4	0
DS2502	C3	MAR '00	25252	0005	Carsem S		DM941226AA	SOIC	4	0
DS2502	C3	JUN '00	25567	0011	Carsem S		DM941230AG	SOIC	4	0
DS5002	C4	APR '00	25429	0004	Carsem		DM925587AAF	MQFP	4	0
DS87C520	A14	FEB '00	25119	0004	ATP (Anam, PI)		DK935356AAB	PLCC	4	0

RELIABILITY MONITOR

STRESS: PHYSICAL DIMENSIONS

CONDITIONS: MIL-STD-883-2016

PRODUCT	REV	MONITOR DATE	JOB NO	DATE ASSEMBLY CODE	FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAIL
DS1230	B1-Y	APR '00	25413	0005	Fastech	118511	Module w/SMT		6	0
DS1230	B1-	JUL '00	25776	0019	Fastech	117143	Module w/SMT		6	0
DS1230	B1-Y	JUL '00	25780	0020	Fastech	11387	Low Profile Module		6	0
DS1230	A1-Y	OCT '00	26095	0039	Fastech	120544	Module w/SMT		6	0
DS12887	A2-	JUL '00	25806	0027	Fastech	300063	Module w/Bent Fra		6	0
DS12887	A2-	OCT '00	26070	0040	Fastech	300402	Module w/Bent Fra		6	0
DS1643	C1	AUG '99	24349	9929	Dallas	111344	Module w/Hi Densit		6	0
DS1643	C1	AUG '00	25918	0033	Fastech	121538	Module w/Hi Densit		6	0
DS1643	C1	NOV '00	26179	0042	Fastech	122271	Module w/Hi Densit		6	0
DS5000	D6-T	MAY '00	25531	0020	Dallas	117838	SBDIP		2	0

RELIABILITY MONITOR

STRESS: MOISTURE SOAK

CONDITIONS: 60C/90% R.H.

PRODUCT	REV	MONITOR DATE	JOB NO	DATE ASSEMBLY CODE	FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAIL
DS1230	B1-Y	APR '00	25416	0005	Fastech	118511	Module w/SMT	288	100	0
DS1230	B1-Y	APR '00	25416	0005	Fastech	118511	Module w/SMT	960	100	0
DS1230	B1-	JUL '00	25779	0019	Fastech	117143	Module w/SMT	288	100	0
DS1230	B1-	JUL '00	25779	0019	Fastech	117143	Module w/SMT	960	99	0
DS1230	A1-Y	OCT '00	26098	0039	Fastech	120544	Module w/SMT	288	100	0
DS1643	C1	AUG '99	24352	9929	Dallas	111344	Module w/Hi Densit	288	77	0
DS1643	C1	AUG '99	24352	9929	Dallas	111344	Module w/Hi Densit	960	77	1
DS1644	B2	MAY '00	25686	0021	Dallas	119504	Power Cap	288	77	0
DS1991	E8	JUN '00	25551	0021	Dallas	DS950013AA-	T5 w/welded Tabs	288	77	0
DS1991	E8	JUN '00	25551	0021	Dallas	DS950013AA-	T5 w/welded Tabs	960	77	0
DS1991	F1	SEP '00	25939	0036	Dallas	DS922809AA-	Puk Can F50 Rev B	288	77	0
DS2250	E-T	SEP '00	25964	0035	Fastech	117888	SipStick w/Confor	192	11	0
DS5000	D6-T	FEB '00	25200	0006	Dallas	115605	SBDIP	288	15	0
DS5000	D6-T	FEB '00	25200	0006	Dallas	115605	SBDIP	960	15	0
DS5000	D6-T	MAY '00	25534	0020	Dallas	117838	SBDIP	288	15	0
DS5000	D6-T	MAY '00	25534	0020	Dallas	117838	SBDIP	960	15	1

RELIABILITY MONITOR

STRESS: INFANT LIFE

CONDITIONS: 85C

PRODUCT	REV	MONITOR DATE	JOB NO	DATE ASSEMBLY CODE FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAIL
DS12887	A2-	JUL '00	25807	0027 Fastech	300063	Module w/Bent Fra	48	200	0
DS12887	A2-	OCT '00	26071	0040 Fastech	300402	Module w/Bent Fra	48	200	0

RELIABILITY MONITOR

STRESS: HAST, NO BIAS

CONDITIONS: 130C, 85% R.H.

PRODUCT	REV	MONITOR DATE	JOB NO	DATE ASSEMBLY CODE FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAIL
DS2154	A2	SEP '00	25961	0034 ATP (Anam, PI)	DK022283AAA	LQFP	200	64	0
DS21Q43	A3-A	JUN '00	25508	0014 ATK (Anam, K)	DN004571AAB	LQFP	100	38	0

RELIABILITY MONITOR

STRESS: HAST, NO BIAS

CONDITIONS: 130C, 85%R.H.,5.5V

PRODUCT	REV	MONITOR DATE	JOB NO	DATE ASSEMBLY CODE	FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAIL
DS2154	A2	JUN '00	25623	0022	ATK (Anam, K)	DN012234ABA	LQFP	100	73	3

RELIABILITY MONITOR

STRESS: HAST

CONDITIONS: 130C, 85%R.H.,5.5V

PRODUCT	REV	MONITOR DATE	JOB NO	DATE ASSEMBLY CODE FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAIL
DS1232	C2-L	JAN '00	25025	9948 ATP (Anam, PI)	DK933191AAJ	SOIC	100	77	1
DS1232	C2-L	APR '00	25424	0011 OSEP	DE952427AAD	SOIC	100	76	0
DS1232	C2-L	JUL '00	25790	0024 OSEP	DE014522ADB	SOIC	100	76	0
DS2401	C2	SEP '00	25968	0034 Fastech	DA005635AKA	TO92	100	77	0
DS2434	D1	AUG '99	24394	9837 Carsem	DM811482AA	TO226 (PR35)	100	69	0
DS87C520	A14	FEB '00	25123	0004 ATP (Anam, PI)	DK935356AAB	PLCC	100	58	0

RELIABILITY MONITOR

STRESS: CONVECTION REFLOW

CONDITIONS: 220C

PRODUCT	REV	MONITOR	DATE	ASSEMBLY	LOT NO.	PACKAGE	READ	POINT	QTY	FAIL
DS3816	A-C	& DS3801	26051	0041 Dallas	120701	BGA Module	2	99	0	

RELIABILITY MONITOR

STRESS: CONVECTION REFLOW

CONDITIONS: 235C

PRODUCT	REV	MONITOR		DATE	ASSEMBLY		LOT NO.	PACKAGE	READ		
		DATE	JOB NO		CODE	FACILITY			POINT	QTY	FAIL
DS1232	C2-L	JAN '00	25020	9948	ATP (Anam, PI)	DK933191AAJ	SOIC	3	238	0	
DS1232	C2-L	APR '00	25419	0011	OSEP	DE952427AAD	SOIC	3	238	0	
DS1232	C2-L	JUL '00	25785	0024	OSEP	DE014522ADB	SOIC	3	238	0	
DS1232	C2-L	OCT '00	26087	0039	OSEP	DE028679ADB	SOIC	3	238	0	
DS1267	A2	FEB '00	25173	9930	ATP (Anam, PI)	DK904472ADF	TSSOP	3	238	0	
DS1621	A7	MAR '00	25218	9950	OSEP	DE940040AAC	SOIC	3	241	0	
DS1869	A3	JUN '00	25541	0017	CPS (ChipPac, China)	DH833210AAB	SOIC	3	241	0	
DS2108	B7	MAY '00	25523	0019	ATP (Anam, PI)	DK007198AAF	SOIC	3	238	3	
DS2108	B7	AUG '00	25855	0029	ATP (Anam, PI)	DK016058AA	SOIC	3	238	0	
DS2118M	B1	SEP '00	25941	0033	ATK (Anam, K)	DN020718AAD	SSOP	3	238	0	
DS2154	A2	JUN '00	25618	0022	ATK (Anam, K)	DN012234ABA	LQFP	3	238	1	
DS2154	A2	SEP '00	25956	0034	ATP (Anam, PI)	DK022283AAA	LQFP	3	238	0	
DS2175	D1	OCT '00	26106	0042	ATP (Anam, PI)	DK031506AAC	SOIC	3	238	0	
DS21Q43	A3-A	JUN '00	25502	0014	ATK (Anam, K)	DN004571AAB	LQFP	3	239	0	
DS21Q43	A3-A	SEP '00	25948	0031	Stats	DC022318AAD	LQFP	3	239	0	
DS21S07	C1-	MAY '00	25444	0013	Carsem S	DM002285AAF	TSSOP	3	238	0	
DS2502	C3	MAR '00	25251	0005	Carsem S	DM941226AA	SOIC	3	238	0	
DS2502	C3	JUN '00	25566	0011	Carsem S	DM941230AG	SOIC	3	238	0	
DS2502	C3	JUL '00	25811	0017	CPS (ChipPac, China)	DH948636AG	TSOC	3	151	0	

RELIABILITY MONITOR

STRESS: BIASED MOISTURE

CONDITIONS: 85/85, 5.5 VOLTS

PRODUCT	REV	MONITOR DATE	JOB NO	DATE ASSEMBLY CODE	FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAIL
DS1267	A2	FEB '00	25178	9930	ATP (Anam, PI)	DK904472ADF	TSSOP	274	77	0
DS12887	A2-	JUL '00	25809	0027	Fastech	300063	Module w/Bent Fra	274	100	0
DS1302	A3	MAR '00	25214	0006	CPS (ChipPac, China)	DH945115AAB	PDIP	274	77	0
DS1302	A3	MAR '00	25214	0006	CPS (ChipPac, China)	DH945115AAB	PDIP	959	77	0
DS1302	A3	JUN '00	25538	0018	CPS (ChipPac, China)	DH008331AAA	PDIP	274	77	0
DS1302	A3	JUN '00	25538	0018	CPS (ChipPac, China)	DH008331AAA	PDIP	959	77	1
DS1302	A3	AUG '00	25934	0032	CPS (ChipPac, China)	DH020619AAA	PDIP	274	77	0
DS1621	A7	MAR '00	25223	9950	OSEP	DE940040AAC	SOIC	274	70	0
DS1621	A7	MAR '00	25223	9950	OSEP	DE940040AAC	SOIC	959	69	0
DS2108	B7	MAY '00	25528	0019	ATP (Anam, PI)	DK007198AAF	SOIC	274	77	1
DS2108	B7	MAY '00	25528	0019	ATP (Anam, PI)	DK007198AAF	SOIC	959	76	0
DS2108	B7	AUG '00	25860	0029	ATP (Anam, PI)	DK016058AA	SOIC	274	77	3
DS2108	B7	AUG '00	25860	0029	ATP (Anam, PI)	DK016058AA	SOIC	959	74	0
DS21Q43	A3-A	JUN '00	25507	0014	ATK (Anam, K)	DN004571AAB	LQFP	274	39	0
DS21S07	C1-	MAY '00	25449	0013	Carsem S	DM002285AAF	TSSOP	274	77	0
DS21S07	C1-	MAY '00	25449	0013	Carsem S	DM002285AAF	TSSOP	959	77	0
DS2502	C3	MAR '00	25256	0005	Carsem S	DM941226AA	SOIC	959	77	0
DS2502	C3	JUN '00	25571	0011	Carsem S	DM941230AG	SOIC	274	77	0
DS5002	C4	APR '00	25433	0004	Carsem	DM925587AAF	MQFP	274	40	0
DS5002	C4	APR '00	25433	0004	Carsem	DM925587AAF	MQFP	959	40	0
DS80C320	C5	JAN '00	25017	0001	CPS (ChipPac, China)	DH928322BAA	PDIP	274	77	0
DS80C320	C5	JAN '00	25017	0001	CPS (ChipPac, China)	DH928322BAA	PDIP	959	77	0

RELIABILITY MONITOR

STRESS: BIASED MOISTURE

CONDITIONS: 85/85, 5.5 VOLTS

PRODUCT	REV	MONITOR DATE	JOB NO	DATE ASSEMBLY CODE	FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAIL
DS80C320	C5	OCT '00	26067	0038	CPS (ChipPac, China)	DH026369ABA	PDIP	274	77	0

RELIABILITY MONITOR

STRESS: AUTOCLAVE

CONDITIONS: 121C, 2 ATM STEAM, UNBIASED

PRODUCT	REV	MONITOR		DATE ASSEMBLY		LOT NO.	PACKAGE	READ		
		DATE	JOB NO	CODE	FACILITY			POINT	QTY	FAIL
DS1232	C2-L	JAN '00	25026	9948	ATP (Anam, PI)	DK933191AAJ	SOIC	96	38	0
DS1232	C2-L	APR '00	25425	0011	OSEP	DE952427AAD	SOIC	96	40	0
DS1232	C2-L	JUL '00	25791	0024	OSEP	DE014522ADB	SOIC	96	39	0
DS1232	C2-L	OCT '00	26093	0039	OSEP	DE028679ADB	SOIC	96	39	0
DS1267	A2	FEB '00	25179	9930	ATP (Anam, PI)	DK904472ADF	TSSOP	96	36	0
DS1302	A3	MAR '00	25215	0006	CPS (ChipPac, China)	DH945115AAB	PDIP	96	39	0
DS1302	A3	JUN '00	25539	0018	CPS (ChipPac, China)	DH008331AAA	PDIP	96	40	0
DS1302	A3	AUG '00	25935	0032	CPS (ChipPac, China)	DH020619AAA	PDIP	96	38	0
DS2108	B7	MAY '00	25529	0019	ATP (Anam, PI)	DK007198AAF	SOIC	96	37	0
DS2108	B7	AUG '00	25861	0029	ATP (Anam, PI)	DK016058AA	SOIC	96	33	0
DS2118M	B1	SEP '00	25946	0033	ATK (Anam, K)	DN020718AAD	SSOP	96	77	0
DS21S07	C1-	MAY '00	25450	0013	Carsem S	DM002285AAF	TSSOP	96	40	0
DS2401	C2	SEP '00	25969	0034	Fastech	DA005635AKA	TO92	96	39	0
DS2434	D1	AUG '99	24395	9837	Carsem	DM811482AA	TO226 (PR35)	96	37	0
DS2502	C3	JUL '00	25814	0017	CPS (ChipPac, China)	DH948636AG	TSOC	96	70	0
DS5002	C4	APR '00	25434	0004	Carsem	DM925587AAF	MQFP	96	39	0
DS5002	C5	JUL '00	25830	0027	ATK (Anam, K)	DN012259AAL	MQFP	96	37	0
DS80C320	C5	JAN '00	25018	0001	CPS (ChipPac, China)	DH928322BAA	PDIP	96	40	0
DS80C320	C5	OCT '00	26068	0038	CPS (ChipPac, China)	DH026369ABA	PDIP	96	37	0

RELIABILITY MONITOR

STRESS: 0 HR TEST

CONDITIONS: Connect Cap & Base

PRODUCT	REV	MONITOR DATE	JOB NO	DATE ASSEMBLY CODE FACILITY	LOT NO.	PACKAGE	READ POINT	QTY	FAIL
DS1644	B2	MAY '00	25683	0021 Dallas	119504	Power Cap	2	231	0